ON Semiconductor

Is Now

Onsemi

To learn more about onsemi[™], please visit our website at <u>www.onsemi.com</u>

onsemi and ONSEMI. and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product factures, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and asfety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or by customer's technical experts. onsemi products and actal performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use onsemi products for any such unintended or unauthorized application, Buyer shall indemnify and hold onsemi and its officers, employees, subsidiari

September 2017



FDPF035N06B N-Channel PowerTrench[®] MOSFET $60 V, 88 A, 3.5 m\Omega$

Features

- $R_{DS(on)}$ = 2.91 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 88 A
- Low FOM R_{DS(on)}*Q_G

ON Semiconductor®

- Low Reverse Recovery Charge, Qrr
- Soft Reverse Recovery Body Diode
- Enables Highly Efficiency in Synchronous Rectification
- Fast Switching Speed
- 100% UIL Tested
- RoHS Compliant

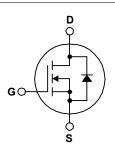
Description

This N-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench[®] process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies
- Renewable System





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

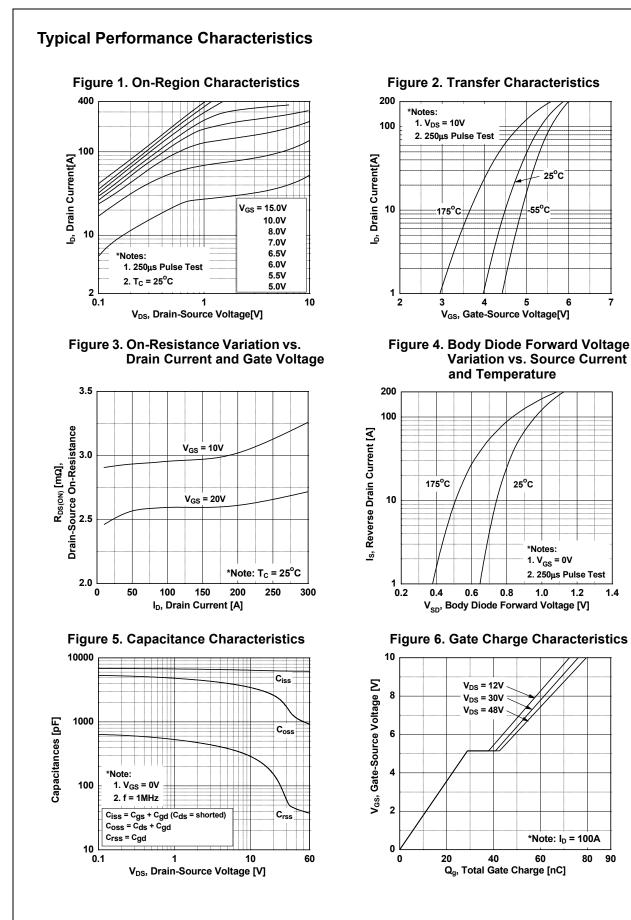
Symbol	Parameter			FDPF035N06B-F152	Unit	
V _{DSS}	Drain to Source Voltage			60	V	
V _{GSS}	Gate to Source Voltage			±20	V	
I _D	Drain Current	- Continuous (T _C = 25 ^o C, Sili	- Continuous (T _C = 25°C, Silicon Limited)		A	
	Drain Current	- Continuous (T _C = 100°C, S	- Continuous (T _C = 100°C, Silicon Limited)			
I _{DM}	Drain Current	- Pulsed	(Note 1)	352	А	
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	600	mJ	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	6.0	V/ns	
P _D	Dower Dissinction	(T _C = 25°C)	(T _C = 25°C)		W	
	Power Dissipation	- Derate Above 25°C	- Derate Above 25°C		W/ºC	
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +175	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds			300	°C	

Thermal Characteristics

Symbol	Parameter	FDPF035N06B-F152	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	3.24	°C/W
R_{\thetaJA}	Thermal Resistance, Junction to Ambient, Max.	62.5	0/11

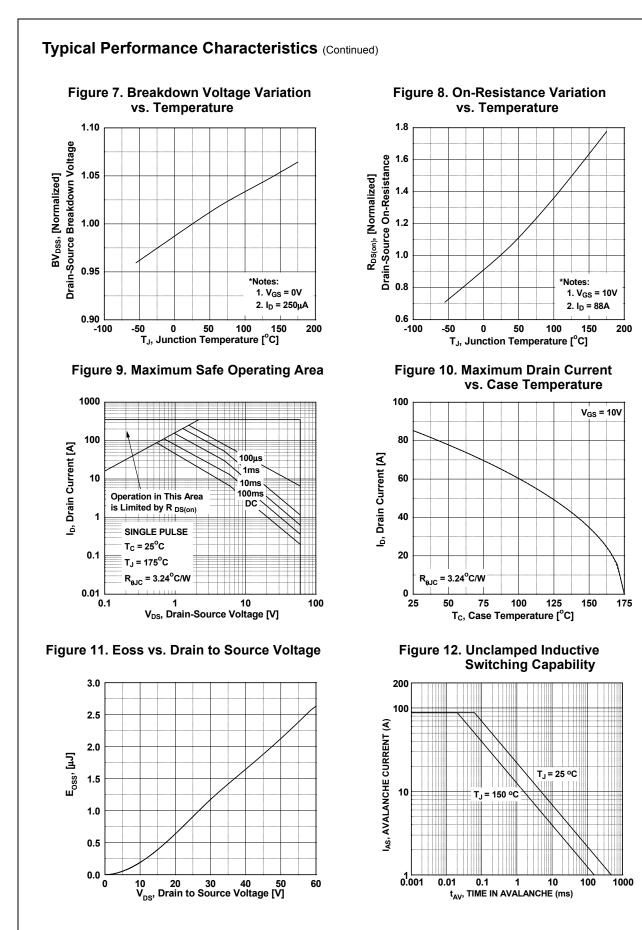
1

6B-F152	FDPF035N06B	Top MarkPackagePacking MetFDPF035N06BTO-220FTube		Reel Size N/A		Tape Width N/A	Quantity 50 units	
Charac	cteristics T _C = 25	5°C unless oth	nerwise noted.					
Symbol Parameter			Test Conditions		Min.	Тур.	Max.	Unit
eristics								
Drain to Source Breakdown Voltage		age Ir	I _D = 250 μA, V _{GS} = 0 V		60	-	_	V
			$I_D = 250 \ \mu\text{A}$, Referenced to 25°C		-	0.03	-	V/ºC
Zero Gate	te Voltage Drain Current		V _{DS} = 48 V, V _{GS} = 0 V		-	-	1	μA
Gate to Bo	Body Leakage Current		V _{GS} = ±20 V, V _{DS} = 0 V		-	-	±100	nA
eristics								
Gate Thre	Gate Threshold Voltage		$V_{GS} = V_{DS}, I_{D} = 250 \ \mu A$		2	-	4	V
Static Drai	tic Drain to Source On Resistance		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 88 \text{ A}$		-	2.91	3.5	mΩ
Forward T	Forward Transconductance		V _{DS} = 10 V, I _D = 88 A		-	176	-	S
naracteri	stics							
Input Capa	acitance		V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz		-	6035	8030	pF
					-	1685	2240	pF
Reverse T	ransfer Capacitance	T			-	55	-	pF
		nce V	/ _{DS} = 30 V, V _{GS} = 0 V		-	2619	-	pF
					-	76	99	nC
Gate to Sc	ource Gate Charge		$V_{DS} = 30 \text{ V}, \text{ I}_{D} = 100 \text{ A},$ $V_{GS} = 10 \text{ V}$		-	29	-	nC
Gate to Dr	ain "Miller" Charge	V			-	12	-	nC
Gate Plate	au Volatge			(Note 4)	-	5.2	-	V
Total Gate	Charge Sync.	V	/ _{DS} = 0 V, I _D = 50 A		-	67.3	-	nC
Output Ch	arge	V	/ _{DS} = 30 V, V _{GS} = 0 V		-	92.4	-	nC
Equivalent	Series Resistance (G	-S) f	= 1 MHz		-	2.0	-	Ω
Characte	ristics							
Turn-On D					-	32	74	ns
Turn-On R	ise Time			_	-	33	76	ns
Turn-Off D	elay Time	V	V_{GS} = 10 V, R_{G} = 4.7 Ω		-	56	122	ns
Turn-Off Fa	all Time			(Note 4)	-	23	56	ns
e Diode	Characteristics	l						
				-	-	88	А	
					-	-		A
					-	-	1.25	V
		ů.			-	71	-	ns
Reverse R	ecovery Charge		$dI_{F}/dt = 100 A/\mu s$		-	78	-	nC
	eristics Drain to So Breakdown Coefficient Zero Gate Gate to Bo eristics Gate Three Static Drai Forward T haracteri Input Capa Output Cap Reverse T Energy Re Total Gate Gate to Dr Gate Plate Total Gate Output Cha Equivalent Character Turn-On D Turn-On R Turn-Off D Turn-Off Fa Cab Diode Maximum M Drain to So Reverse R	Parameter eristics Drain to Source Breakdown Volta Breakdown Voltage Temperature Coefficient Zero Gate Voltage Drain Current Gate to Body Leakage Current eristics Gate Threshold Voltage Static Drain to Source On Resist Forward Transconductance naracteristics Input Capacitance Output Capacitance Energy Related Output Capacitan Total Gate Charge at 10V Gate to Source Gate Charge Gate Plateau Volatge Total Gate Charge Sync. Output Charge Equivalent Series Resistance (Green Streamed Strea	ParametereristicsDrain to Source Breakdown VoltageIrBreakdown Voltage Temperature CoefficientIrZero Gate Voltage Drain CurrentVGate to Body Leakage CurrentVGate to Body Leakage CurrentVeristicsStatic Drain to Source On ResistanceVForward TransconductanceVnaracteristicsInput CapacitanceVOutput CapacitancefReverse Transfer CapacitanceFEnergy Related Output CapacitanceVGate to Drain "Miller" ChargeVGate to Drain "Miller" ChargeVGate Plateau VolatgeVTotal Gate Charge Sync.VOutput ChargeVEquivalent Series Resistance (G-S)fCharacteristicsTurn-On Delay TimeTurn-On Rise TimeVTurn-Off Delay TimeVTurn-Off Fall TimeVMaximum Continuous Drain to Source Diode Forward VoltageReverse Recovery TimeV	ParameterTest ConditioneristicsDrain to Source Breakdown Voltage $I_D = 250 \ \mu$ A, $V_{GS} = 0 \ V$ Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, ReferencedZero Gate Voltage Drain Current $V_{DS} = 48 \ V, V_{GS} = 0 \ V$ Gate to Body Leakage Current $V_{DS} = 48 \ V, V_{DS} = 0 \ V$ eristicsStatic Drain to Source On Resistance $V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$ Gate to Dady Leakage Current $V_{GS} = 10 \ V, I_D = 88 \ A$ Forward Transconductance $V_{DS} = 10 \ V, I_D = 88 \ A$ Forward Transconductance $V_{DS} = 10 \ V, I_D = 88 \ A$ ParacteristicsInput Capacitance $V_{DS} = 30 \ V, V_{GS} = 0 \ V, f = 1 \ MHz$ Reverse Transfer Capacitance $V_{DS} = 30 \ V, V_{GS} = 0 \ V$ Gate to Drain "Miller" Charge $V_{DS} = 30 \ V, I_D = 100 \ A, V_{GS} = 10 \ V$ Gate Charge Sync. $V_{DS} = 30 \ V, I_D = 50 \ A$ Output Charge $V_{DS} = 30 \ V, I_D = 50 \ A$ Output Charge $V_{DS} = 30 \ V, I_D = 50 \ A$ Output Charge $V_{DS} = 30 \ V, I_D = 50 \ A$ Output Charge $V_{DS} = 30 \ V, I_D = 50 \ A$ Output Charge $V_{DS} = 30 \ V, I_D = 100 \ A, V_{GS} = 0 \ V$ Equivalent Series Resistance (G-S)f = 1 \ MHzCharacteristicsTurn-On Delay TimeTurn-On Delay Time $V_{DS} = 10 \ V, R_G = 4.7 \ \Omega$ Turn-Off Fall Time $V_{GS} = 10 \ V, R_G = 4.7 \ \Omega$ Turn-Off Fall Time $V_{GS} = 0 \ V, I_S = 88 \ A$ Reverse Recovery Time $V_{GS} = 0 \ V, I_S = 100 \ A, R_S = 0 \ V, I_S = 100 \ A, R$	ParameterTest ConditionseristicsDrain to Source Breakdown VoltageIp = 250 μ A, V _{GS} = 0 VBreakdown Voltage TemperatureIp = 250 μ A, Referenced to 25°CZero Gate Voltage Drain CurrentV _{DS} = 48 V, V _{GS} = 0 VGate to Body Leakage CurrentV _{GS} = ±20 V, V _{DS} = 0 VeristicsGate Threshold VoltageV _{GS} = 10 V, Ip = 88 AForward TransconductanceV _{DS} = 10 V, Ip = 88 AForward TransconductanceV _{DS} = 30 V, V _{GS} = 0 V,f = 1 MHzForward TransconductanceNutput CapacitanceV _{DS} = 30 V, V _{GS} = 0 V,f = 1 MHzForward TransconductanceReverse Transfer CapacitanceV _{DS} = 30 V, V _{GS} = 0 V,f = 1 MHzForward TransconductanceReverse Transfer CapacitanceV _{DS} = 30 V, V _{GS} = 0 V,Gate to Source Gate ChargeV _{DS} = 30 V, V _{GS} = 0 V,Gate to Drain "Miller" ChargeV _{DS} = 30 V, V _{GS} = 0 V,Gate Drain "Miller" ChargeV _{DS} = 30 V, V _{GS} = 0 V,Gate Charge Sync.V _{DS} = 30 V, V _{GS} = 0 V,CharacteristicsV _{DS} = 30 V, V _{GS} = 0 V,Turn-On Delay TimeV _{DS} = 30 V, V _{GS} = 0 V,Turn-On Delay TimeV _{DS} = 30 V, V _S = 100 A,Turn-Off Fall Time(Note 4) colode Characteristics Maximum Continuous Drain to Source Diode Forward CurrentMaximum Continuous Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward CurrentMaximum Pulsed Drain to Source Diode Forward Cu	ParameterTest ConditionsMin.eristicsDrain to Source Breakdown Voltage $I_D = 250 \ \mu$ A, $V_{GS} = 0 \ V$ 60Breakdown Voltage Temperature Coefficient $I_D = 250 \ \mu$ A, Referenced to 25° C-Zero Gate Voltage Drain Current $V_{DS} = 48 \ V, V_{GS} = 0 \ V$ -Gate to Body Leakage Current $V_{GS} = \pm 20 \ V, \ V_{DS} = 0 \ V$ -eristicsGate Threshold Voltage $V_{GS} = V_{DS}, \ I_D = 250 \ \mu$ A2Static Drain to Source On Resistance $V_{GS} = 10 \ V, \ I_D = 88 \ A$ -Forward Transconductance $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 88 \ A$ -nutre Capacitance $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 88 \ A$ -Reverse Transfer Capacitance $f = 1 \ MHz$ -Energy Related Output Capacitance $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 100 \ A, \ V_{CS} = 10 \ V, \ I_D = 50 \ A$ -Gate to Darin "Miller" Charge $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 50 \ A$ -Gate to Darin "Miller" Charge $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 50 \ A$ -Gate to Drain "Miller" Charge $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 50 \ A$ -Total Gate Charge Sync. $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 50 \ A$ -CharacteristicsTurn-On Delay Time $V_{DS} = 30 \ V, \ V_{GS} = 0 \ V, \ I_D = 50 \ A$ -Turn-On Delay Time $V_{DS} = 100 \ A, \ V_{CS} = 10 \ V, \ R_G = 4.7 \ \Omega$ -Turn-Off Fall Time $V_{DS} = 10 \ V, \ R_G = 4.7 \ \Omega$ - </td <td>ParameterTest ConditionsMin.Typ.eristicsDrain to Source Breakdown Voltage$I_D = 250 \ \mu$A, $V_{GS} = 0 \ V$60-Breakdown Voltage Temperature$I_D = 250 \ \mu$A, Referenced to 25°C-0.03Zero Gate Voltage Drain Current$V_{DS} = 48 \ V, V_{GS} = 0 \ V$Gate to Body Leakage Current$V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$eristicsGate to Body Leakage Current$V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$eristicsGate Threshold Voltage$V_{GS} = 10 \ V, I_D = 88 \ A$-176hype Capacitance$V_{DS} = 10 \ V, I_D = 88 \ A$-176prover Transfer Capacitance$V_{DS} = 30 \ V, V_{GS} = 0 \ V$-6035Output Capacitance$V_{DS} = 30 \ V, V_{GS} = 0 \ V$-259Protat Gate Charge at 10V$V_{DS} = 30 \ V, V_{GS} = 0 \ V$-2619Total Gate Charge at 10V$V_{DS} = 30 \ V, I_D = 100 \ A$-229Gate to Drain "Miller" Charge$V_{DS} = 30 \ V, I_D = 50 \ A$-67.3Output Capacitance$V_{DS} = 30 \ V, I_D = 50 \ A$-67.3Output Capacitance$V_{DS} = 30 \ V, I_D = 100 \ A$-22.0Total Gate Charge Sync.$V_{DS} = 30 \ V, I_D = 50 \ A$-67.3Output Charge Sync.$V_{DS} = 30 \ V, I_D = 100 \ A$-22.0Turn-On Delay Time$V_{DS} = 30 \ V, I_D = 100 \ A$-33Turn-On Delay Time$V_{DS} = 30 \ V, I_D = 100 \ A$<td>$\begin{tabular}{ c c c c c } \hline Parameter & Test Conditions & Min. Typ. Max. \\ \hline eristics \\ \hline Prain to Source Breakdown Voltage \$\$ I_D = 250 \ \mu A, V_{GS} = 0 \ V\$ & 60 \$\$ -\$ \$\$ -\$ \$\$ 0.03 \$\$ -\$ \$\$ Coefficient \$\$ I_D = 250 \ \mu A, Referenced to 25^{\circ}C \$\$ -\$ \$\$ 0.03 \$\$ -\$ \$\$ \$\$ Coefficient \$\$ V_{DS} = 48 \ V, V_{GS} = 0 \ V\$ \$\$ -\$ \$\$ -\$ \$\$ 1\$ \$\$ \$\$ \$\$ 10 \ V_{DS} = 48 \ V, V_{DS} = 0 \ V\$ \$\$ -\$ \$\$ -\$ \$\$ \$\$ 10 \ V_{DS} = 48 \ V, V_{DS} = 0 \ V\$ \$\$ -\$ \$\$ -\$ \$\$ \$\$ \$\$ \$\$ \$\$ 10 \ V_{DS} = 250 \ \mu A \$\$ \$\$ \$\$ 2 \$\$ \$\$ \$\$ -\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$</td></td>	ParameterTest ConditionsMin.Typ.eristicsDrain to Source Breakdown Voltage $I_D = 250 \ \mu$ A, $V_{GS} = 0 \ V$ 60-Breakdown Voltage Temperature $I_D = 250 \ \mu$ A, Referenced to 25° C-0.03Zero Gate Voltage Drain Current $V_{DS} = 48 \ V, V_{GS} = 0 \ V$ Gate to Body Leakage Current $V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$ eristicsGate to Body Leakage Current $V_{GS} = \pm 20 \ V, V_{DS} = 0 \ V$ eristicsGate Threshold Voltage $V_{GS} = 10 \ V, I_D = 88 \ A$ -176hype Capacitance $V_{DS} = 10 \ V, I_D = 88 \ A$ -176prover Transfer Capacitance $V_{DS} = 30 \ V, V_{GS} = 0 \ V$ -6035Output Capacitance $V_{DS} = 30 \ V, V_{GS} = 0 \ V$ -259Protat Gate Charge at 10V $V_{DS} = 30 \ V, V_{GS} = 0 \ V$ -2619Total Gate Charge at 10V $V_{DS} = 30 \ V, I_D = 100 \ A$ -229Gate to Drain "Miller" Charge $V_{DS} = 30 \ V, I_D = 50 \ A$ -67.3Output Capacitance $V_{DS} = 30 \ V, I_D = 50 \ A$ -67.3Output Capacitance $V_{DS} = 30 \ V, I_D = 100 \ A$ -22.0Total Gate Charge Sync. $V_{DS} = 30 \ V, I_D = 50 \ A$ -67.3Output Charge Sync. $V_{DS} = 30 \ V, I_D = 100 \ A$ -22.0Turn-On Delay Time $V_{DS} = 30 \ V, I_D = 100 \ A$ -33Turn-On Delay Time $V_{DS} = 30 \ V, I_D = 100 \ A$ <td>$\begin{tabular}{ c c c c c } \hline Parameter & Test Conditions & Min. Typ. Max. \\ \hline eristics \\ \hline Prain to Source Breakdown Voltage \$\$ I_D = 250 \ \mu A, V_{GS} = 0 \ V\$ & 60 \$\$ -\$ \$\$ -\$ \$\$ 0.03 \$\$ -\$ \$\$ Coefficient \$\$ I_D = 250 \ \mu A, Referenced to 25^{\circ}C \$\$ -\$ \$\$ 0.03 \$\$ -\$ \$\$ \$\$ Coefficient \$\$ V_{DS} = 48 \ V, V_{GS} = 0 \ V\$ \$\$ -\$ \$\$ -\$ \$\$ 1\$ \$\$ \$\$ \$\$ 10 \ V_{DS} = 48 \ V, V_{DS} = 0 \ V\$ \$\$ -\$ \$\$ -\$ \$\$ \$\$ 10 \ V_{DS} = 48 \ V, V_{DS} = 0 \ V\$ \$\$ -\$ \$\$ -\$ \$\$ \$\$ \$\$ \$\$ \$\$ 10 \ V_{DS} = 250 \ \mu A \$\$ \$\$ \$\$ 2 \$\$ \$\$ \$\$ -\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$ \$\$</td>	$\begin{tabular}{ c c c c c } \hline Parameter & Test Conditions & Min. Typ. Max. \\ \hline eristics \\ \hline Prain to Source Breakdown Voltage $$ I_D = 250 \ \mu A, V_{GS} = 0 \ V$ & 60 $$ -$ $$ -$ $$ 0.03 $$ -$ $$ Coefficient $$ I_D = 250 \ \mu A, Referenced to 25^{\circ}C $$ -$ $$ 0.03 $$ -$ $$ $$ Coefficient $$ V_{DS} = 48 \ V, V_{GS} = 0 \ V$ $$ -$ $$ -$ $$ 1$ $$ $$ $$ 10 \ V_{DS} = 48 \ V, V_{DS} = 0 \ V$ $$ -$ $$ -$ $$ $$ 10 \ V_{DS} = 48 \ V, V_{DS} = 0 \ V$ $$ -$ $$ -$ $$ $$ $$ $$ $$ 10 \ V_{DS} = 250 \ \mu A $$ $$ $$ 2 $$ $$ $$ -$ $$ $$ $$ $$ $$ $$ $$ $$ $$ $



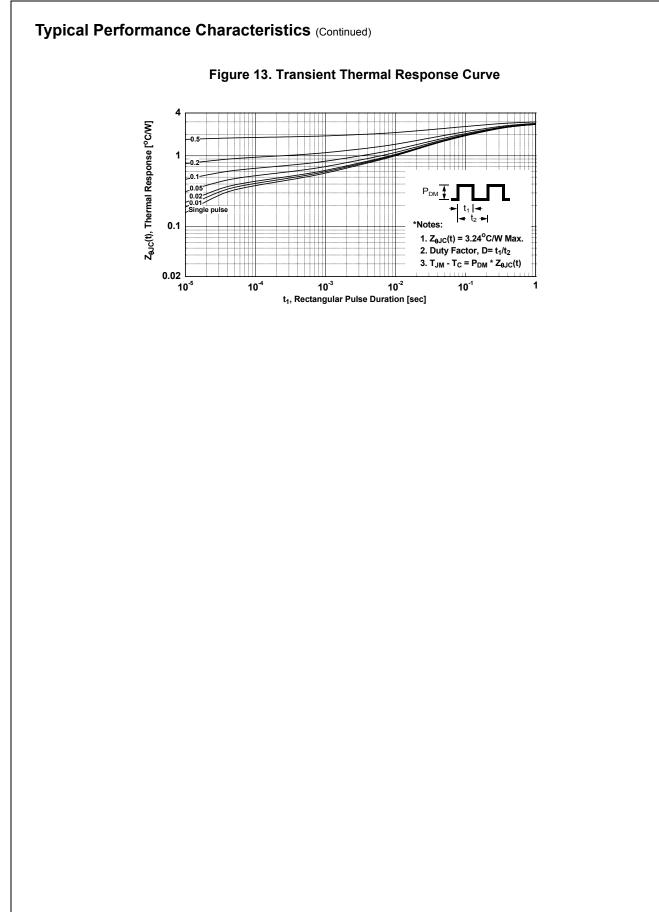
©2013 Semiconductor Components Industries, LLC. FDPF035N06B Rev. 1

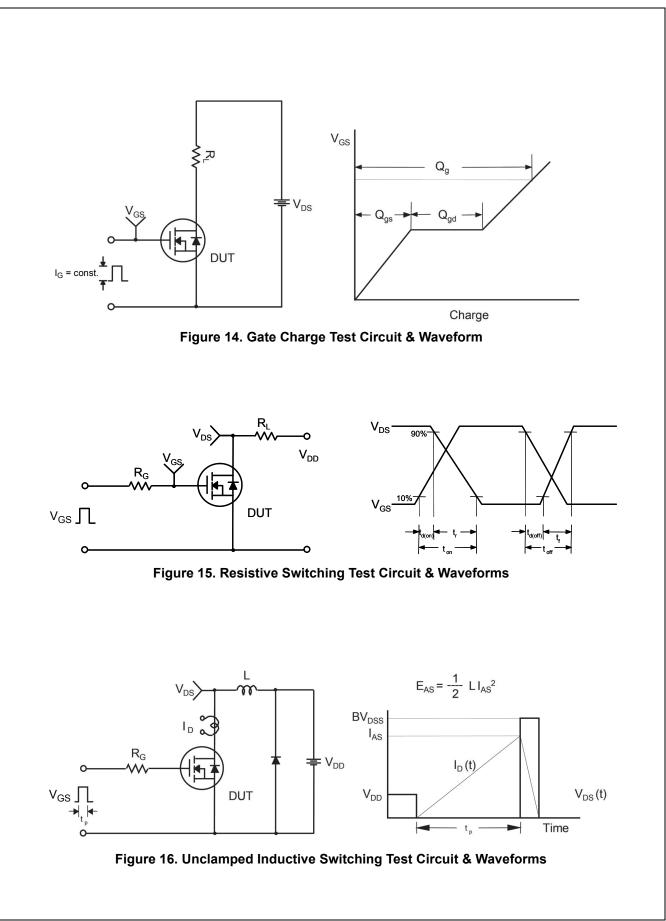




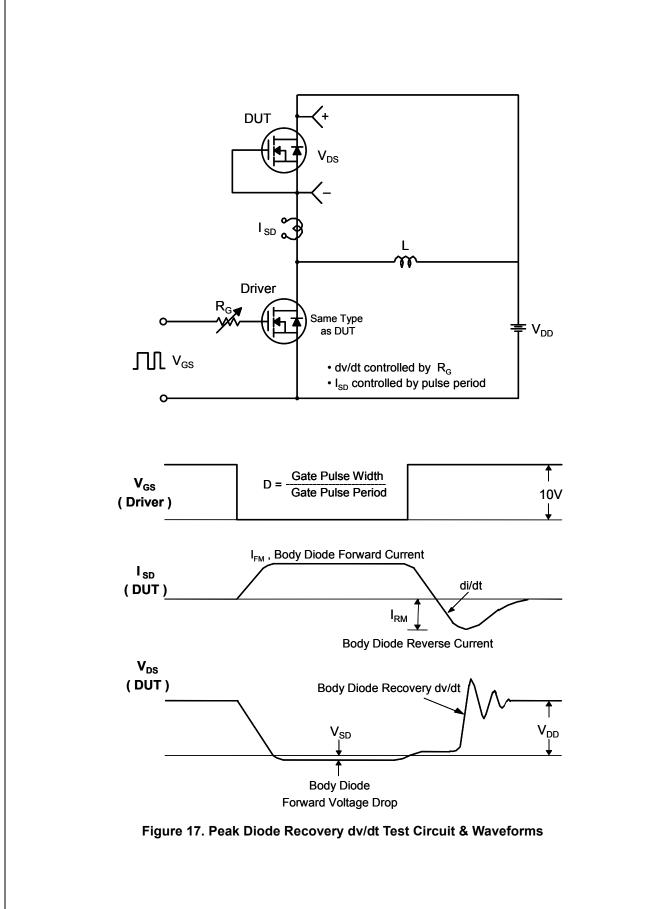
©2013 Semiconductor Components Industries, LLC. FDPF035N06B Rev. 1

4

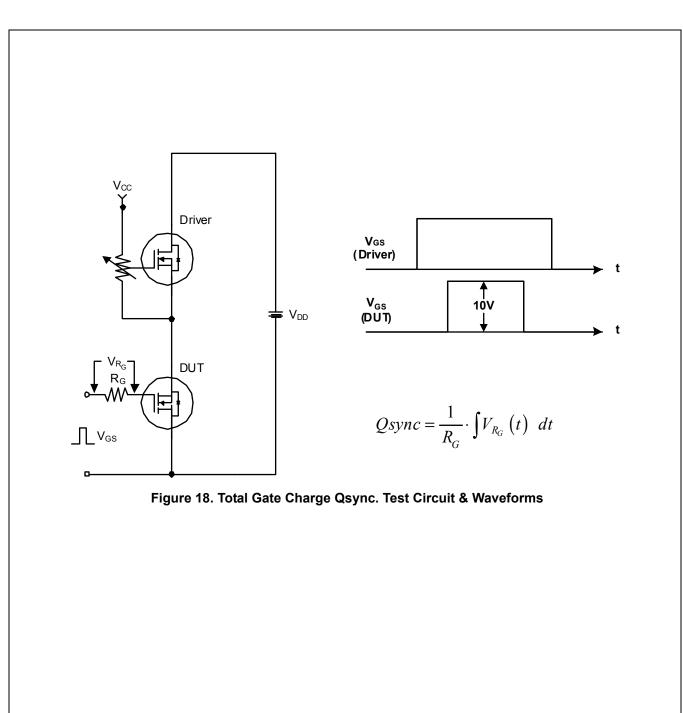




FDPF035N06B — N-Channel PowerTrench[®] MOSFET



FDPF035N06B — N-Channel PowerTrench[®] MOSFET



8

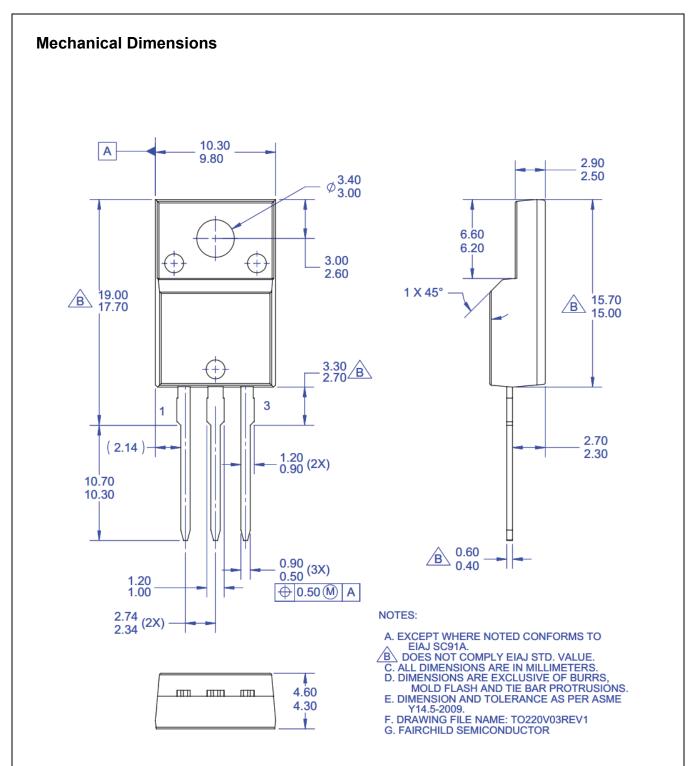


Figure 19. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Takcheong

Package drawings are provided as a service to customers considering ON Semiconductor components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact an ON Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of ON Semiconductor's worldwide terms and conditions, specifically the warranty therein, which covers ON Semiconductor products.

Always visit ON Semiconductor's online packaging area for the most recent package drawings.

FDPF035N06B — N-Channel PowerTrench[®] MOSFET

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor haves, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such uninten

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative